

$V_{RRM}$  = 5500 V  
 $I_{F(AV)M}$  = 635 A  
 $I_{FSM}$  =  $15.5 \cdot 10^3$  A  
 $V_{F0}$  = 2.9 V  
 $r_F$  = 1.9 mΩ  
 $V_{DC-Link}$  = 3300 V

# Fast Recovery Diode

## 5SDF 08H6005

Doc. No. 5SYA1116-02 Apr. 16

- Patented free-floating technology
- Industry standard housing
- Cosmic radiation withstand rating
- Low on-state and switching losses
- Optimized for snubberless operation

### Blocking

*Maximum rated values 1)*

Parameter	Symbol	Conditions	5SDF 08H6005		Unit
Repetitive peak reverse voltage	$V_{RRM}$	$f = 50$ Hz, $t_p = 10$ ms, $T_{vj} = 115$ °C	5500		V
Permanent DC voltage for 100 FIT failure rate	$V_{DC-link}$	Ambient cosmic radiation at sea level in open air.	3300		V
		100% Duty	3900		

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse leakage current	$I_{RRM}$	$V_{RRM}, T_{vj} = 115$ °C			30	mA

### Mechanical data

*Maximum rated values 1)*

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	$F_M$		36	40	46	kN
Acceleration	a	Device unclamped			50	m/s <sup>2</sup>
Acceleration	a	Device clamped			200	m/s <sup>2</sup>

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				0.83	kg
Housing thickness	H	$F_M = 40$ kN, $T_a = 25$ °C	26.2		26.6	mm
Surface creepage distance	D <sub>s</sub>		30			mm
Air strike distance	D <sub>a</sub>		20			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

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**On-state****Maximum rated values<sup>1)</sup>**

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	I <sub>F(AV)M</sub>	Half sine wave, T <sub>c</sub> = 70 °C			635	A
RMS on-state current	I <sub>F(RMS)</sub>				1000	A
Peak non-repetitive surge current	I <sub>FSM</sub>	t <sub>p</sub> = 10 ms, T <sub>vj</sub> = 115 °C, sine half wave,			15.5 · 10 <sup>3</sup>	A
Limiting load integral	I <sup>2</sup> t	V <sub>R</sub> = 0 V, after surge			1.2 · 10 <sup>6</sup>	A <sup>2</sup> s

**Characteristic values**

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V <sub>F</sub>	I <sub>F</sub> = 1800 A, T <sub>vj</sub> = 115 °C			6.3	V
Threshold voltage	V <sub>F0</sub>				2.9	V
Slope resistance	r <sub>F</sub>	400...2500, T <sub>vj</sub> = 115 °C			1.9	mΩ

**Turn-on****Characteristic values**

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward recovery voltage	V <sub>FRM</sub>	dI <sub>F</sub> /dt = 1000 A/μs, T <sub>vj</sub> = 115 °C			230	V

**Turn-off****Maximum rated values<sup>1)</sup>**

Parameter	Symbol	Conditions	min	typ	max	Unit
Max. decay rate of on-state current	di/dt <sub>crit</sub>	I <sub>FM</sub> = 1800 A, T <sub>vj</sub> = 115 °C, V <sub>DC-Link</sub> = 3300 V			440	A/μs

**Characteristic values**

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	Q <sub>rr</sub>	I <sub>FQ</sub> = 1800 A, V <sub>DC-Link</sub> = 3300 V,			3000	μAs
Reverse recovery current	I <sub>RM</sub>	-di/dt = 440 A/μs, L <sub>CL</sub> = 300 nH, C <sub>CL</sub> = 10 μF, R <sub>CL</sub> = 0.65 Ω,			900	A
Turn-off energy	E <sub>rr</sub>	D <sub>CL</sub> = 5SDF 08H6005, T <sub>vj</sub> = 115 °C			6.5	J

## Thermal

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T <sub>vj</sub>		-40		115	°C
Storage temperature range	T <sub>stg</sub>		-40		125	°C

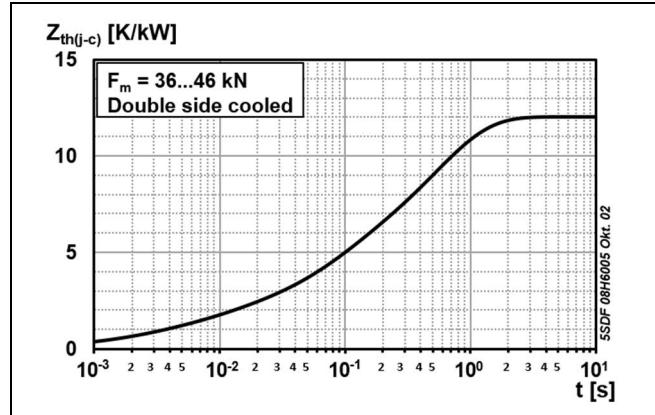
*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	R <sub>th(j-c)</sub>	Double-side cooled F <sub>m</sub> = 36... 46 kN			12	K/kW
	R <sub>th(j-c)A</sub>	Anode-side cooled F <sub>m</sub> = 36... 46 kN			24	K/kW
	R <sub>th(j-c)C</sub>	Cathode-side cooled F <sub>m</sub> = 36... 46 kN			24	K/kW
Thermal resistance case to heatsink	R <sub>th(c-h)</sub>	Double-side cooled F <sub>m</sub> = 36... 46 kN			3	K/kW
	R <sub>th(c-h)</sub>	Single-side cooled F <sub>m</sub> = 36... 46 kN			6	K/kW

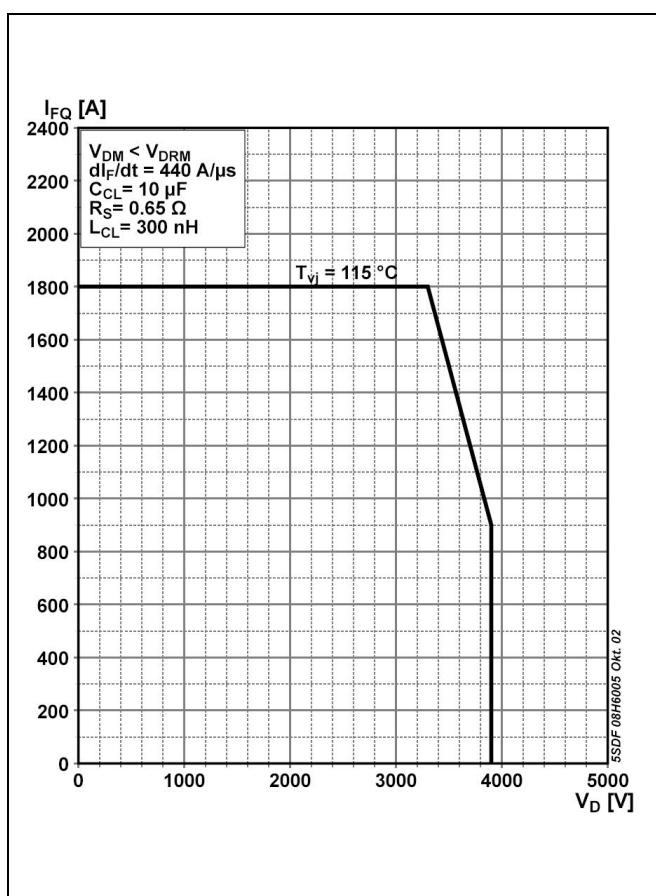
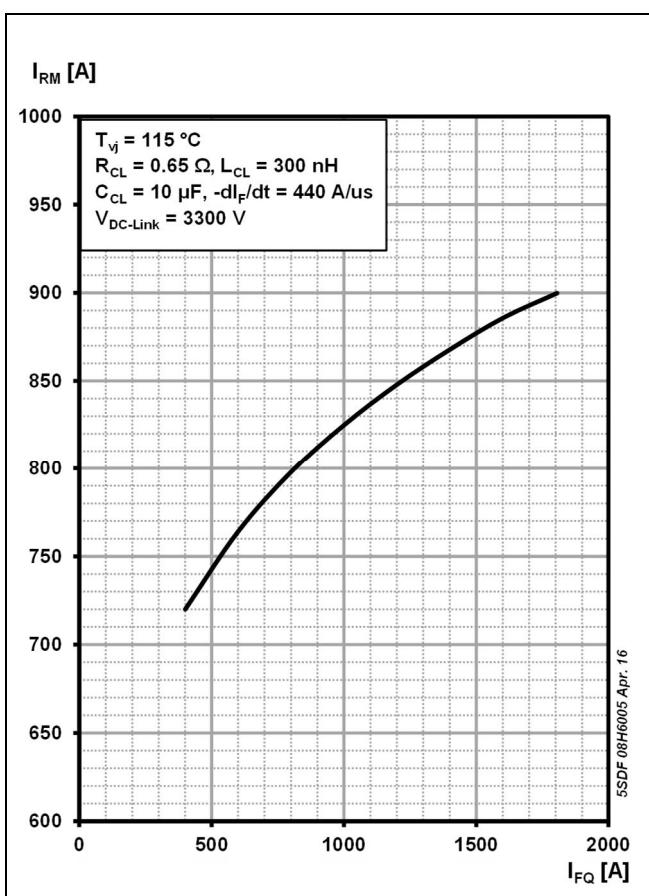
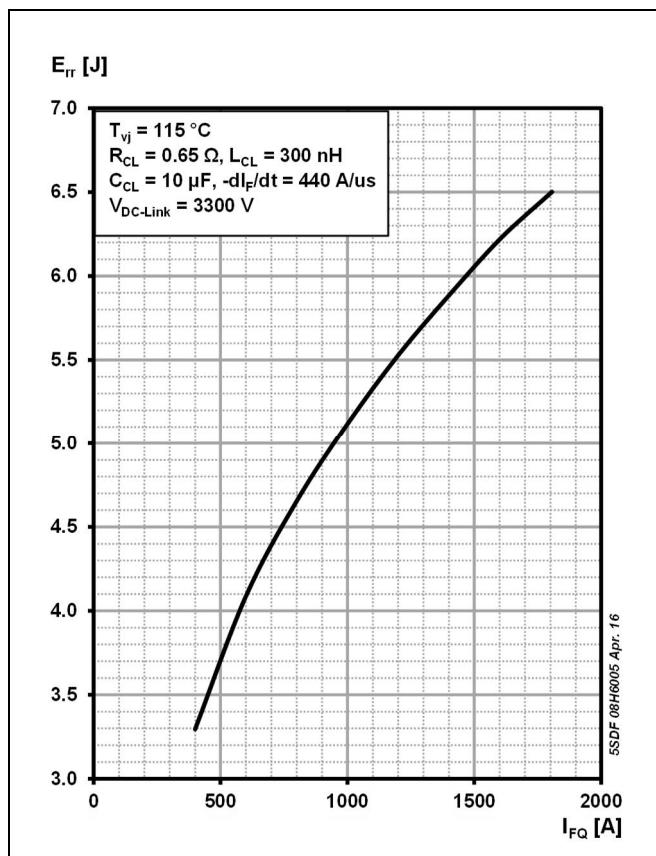
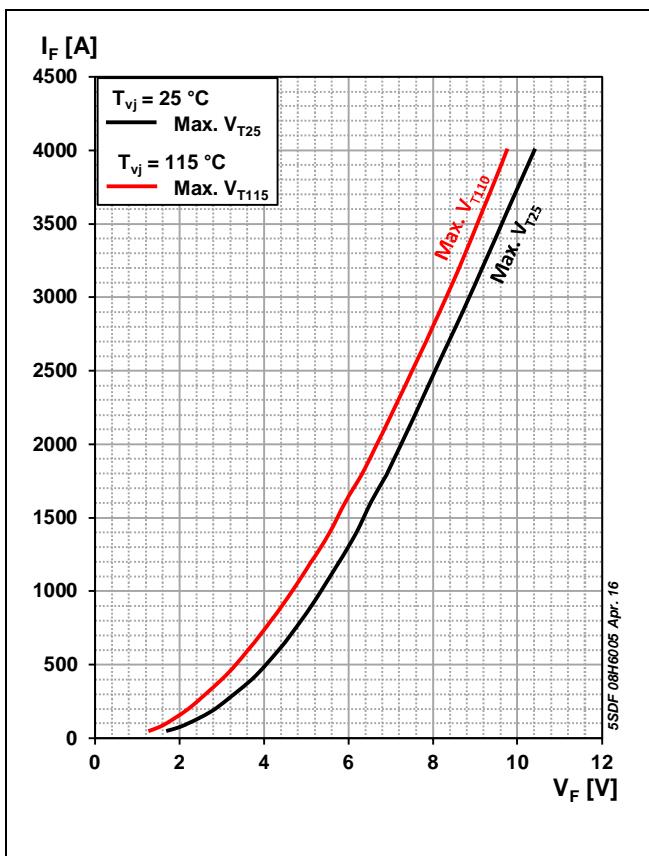
**Analytical function for transient thermal impedance:**

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
R <sub>i</sub> (K/kW)	7.713	2.766	1.044	0.480
τ <sub>i</sub> (s)	0.5316	0.0668	0.0078	0.0020



**Fig. 1** Transient thermal impedance (junction-to-case) vs. time



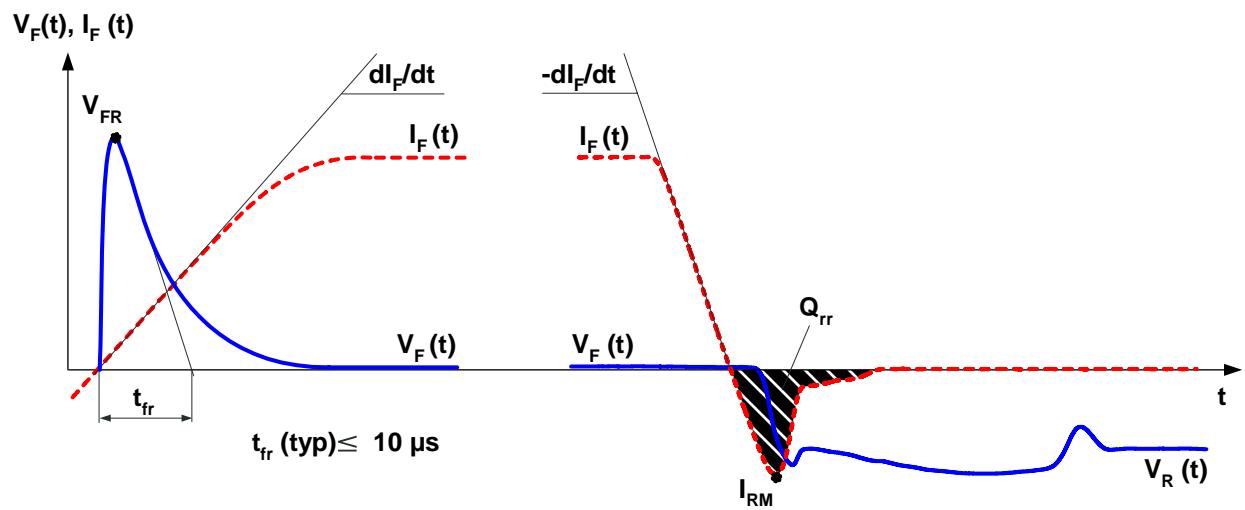


Fig. 6 General current and voltage waveforms

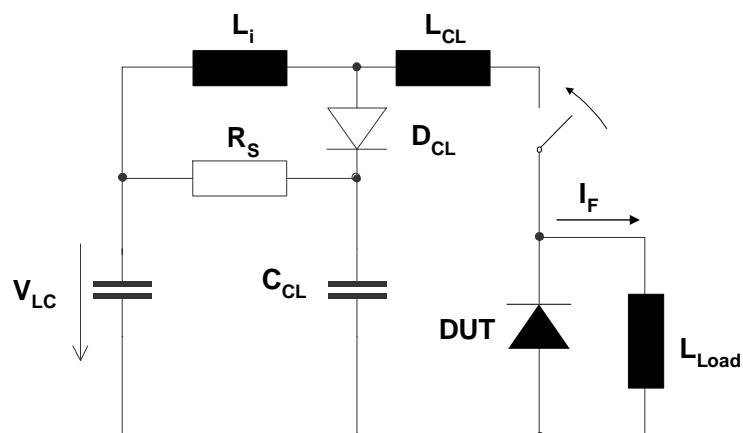
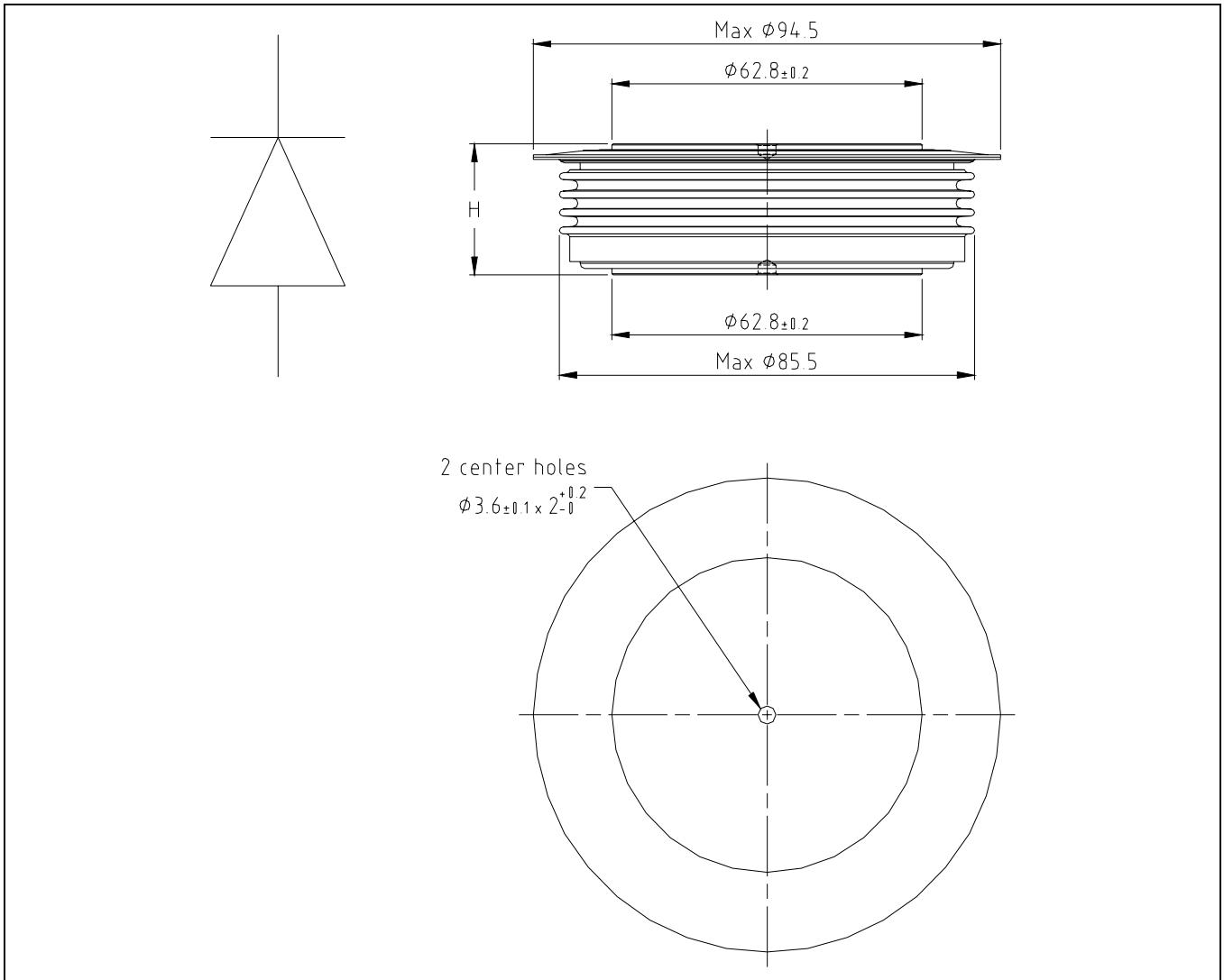


Fig. 7 Test circuit.



**Fig. 8** Device Outline Drawing

### Related documents:

Doc. Nr.	Title
5SYA 2036	Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors
5SYA 2064	Applying Fast Recovery Diodes
5SZK 9104	Specification of environmental class for pressure contact diodes, PCTs and GTO, STORAGE
5SZK 9105	Specification of environmental class for pressure contact diodes, PCTs and GTO, TRANSPORTATION
5SZK 9115	Specification of environmental class for presspack Diodes, PCTs and GTOs, OPERATION (Industry)
5SZK 9116	Specification of environmental class for presspack Diodes, PCTs and GTOs, OPERATION (Traction)

Please refer to <http://www.abb.com/semiconductors> for current version of documents.

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